

Heatsink for PAROLI® Backplane Module

V23814-Z6-Z1

1 General Scope

This data sheet describes the detachable heatsink for PAROLI® Backplane module V23814-x1306-M133¹⁾ (transmitter) resp. V23815-x1306-M133¹⁾ (receiver).

2 Technical Data

See Figure 1.

Dimensions	45 x 24 x 8.75±0.2 mm (L x W x H)
Material	Al Mg 4.5 Mn, black anodized
Coefficient of thermal conduction	110...140 W m ⁻¹ K ⁻¹
No. of fins	14 (1.4 mm width)

3 Application and Assembly

Application is the use of the heatsink to attach onto the module baseplate.

For optimized heat transfer between module and heatsink Infineon recommends to use a heat dissipation foil between both parts (e.g. Panasonic PGS 0.1 mm thickness). Dimensions see **Figure 2**.

The fixing is done by two screws.

Recommendation for screw dimensions: ISO 7045 - M1.6 x 6 - A2 50 - H.

The screws have to be fixed with 10 Ncm.

¹⁾ x = K for 1.25 Gbit/s
 x = U for 1.6 Gbit/s
 x = Q for 2.7 Gbit/s

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4 Package Outlines

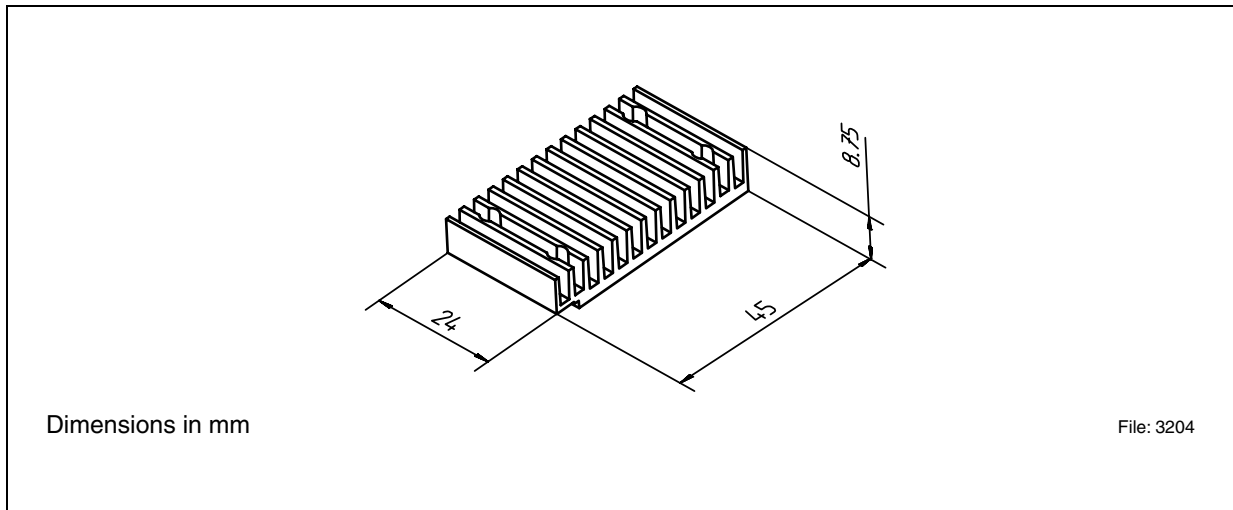


Figure 1 Heatsink PAROLI Backplane Module

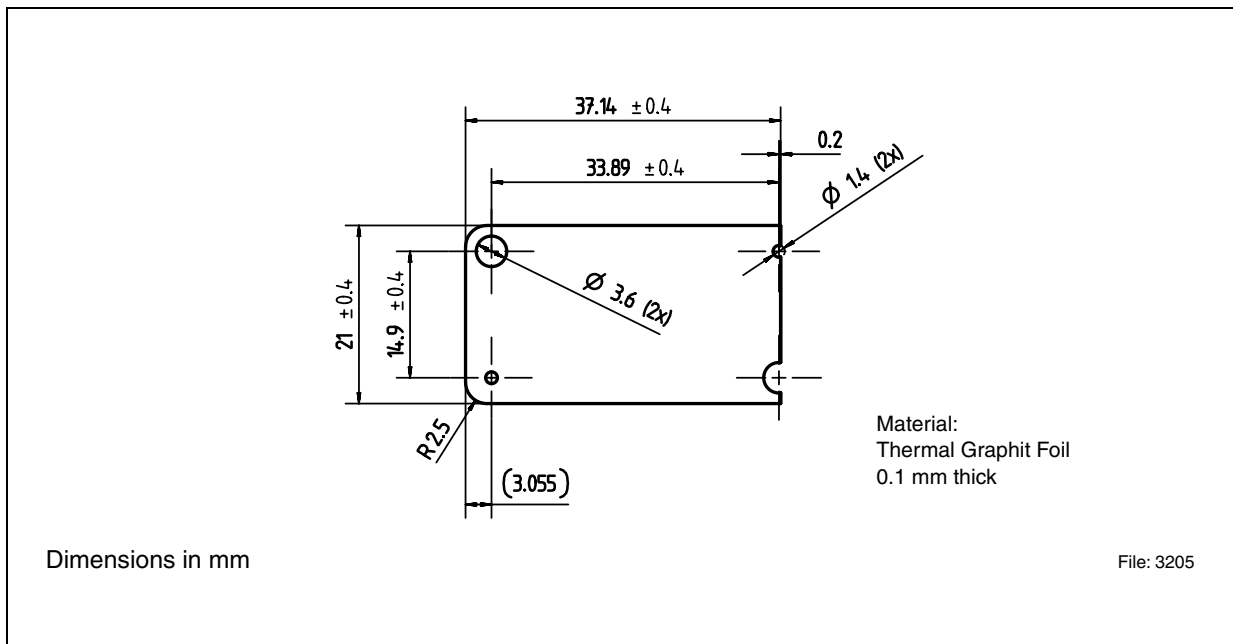


Figure 2 Heat Dissipation Foil

Previous Version:

Page	Subjects (major changes since last revision)

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